


MAXREFDES155#	
Part Number:	
 Property of maxim integrated	Rev 3
Drill and Mechanical Layer	
JAN 17 2016	Units in mils

SHAPE	QTY	SIZE	SYM	PLATED	TOLERANCE
ROUND	234	8	-	YES	+/- 0.003
ROUND	49	12		YES	+/- 0.003
ROUND	12	28		NO	+/- 0.003
ROUND	12	28		YES	+/- 0.003
ROUND	41	39		YES	+/- 0.003

#### Notes:

1. Material: RoHS Compliant FR-408 or similar laminate material
2. Board Dimensions: 4.889 x 3.730 mils
3. Board Thickness: 0.062 mils +/- 20%
4. Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
5. Minimum Trace Width / Trace Spacing: 10mil / 6mil
6. Copper Thickness: 1oz on all layers
7. Surface mount pads: 419
8. Through holes: Quantity = 348, minimum size = 0.008 mil
9. Soldermask: Green
10. Legend: White on Top and Bottom layers
11. Plating: Lead Free
12. Finish: Best finish option for lead free
13. Vendor Logo & date code: OK on back side
14. Testing Needed: Yes
15. Tolerances:

Plated-through holes under BGA chips +/- N/A  
All other plated-through holes +/- 0.003  
Metal to Metal +/- 0.003  
Legend to legend +/- no preference  
Soldermask to Metal +/- 0.003

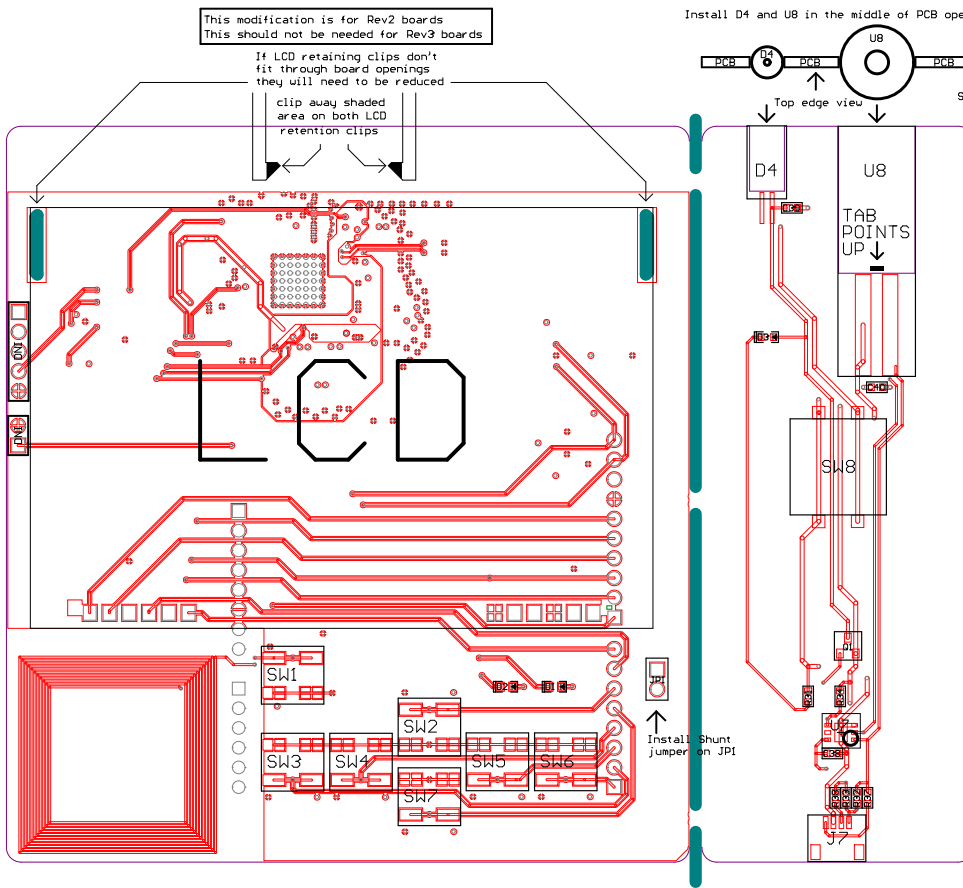


#### Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc

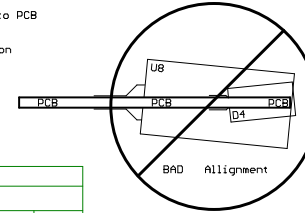
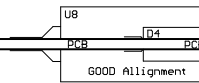
Layer Name	
TOP SILKSCREEN	
TOP METAL	62mil Contour Route Cut
BOTTOM METAL	JATEM MOTT08
BOTTOM SILKSCREEN	W33R02KJ12 MOTT08


Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"



Install D4 and U8 parallel to PCB  
minimize up or down tilt  
D4 and U8 need to 'point'  
in the same angular direction



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Drill and Mechanical Layer	
JAN 17 2016	Units in mils

SHAPE	QTY	SIZES	SYM	PLATED	TOLERANCE
ROUND	234	8	-	YES	+/- 0.003
ROUND	49	12		YES	+/- 0.003
ROUND	12	28		NO	+/- 0.003
ROUND	12	28		YES	+/- 0.003
ROUND	41	39		YES	+/- 0.003

#### Notes:

- Material: RoHS Compliant FR-408 or similar laminate material
- Board Dimensions: 4.889 x 3.730 mils
- Board Thickness: 0.062 mils +/- 20%
- Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
- Minimum Trace Width / Trace Spacing: 10mil / 6mil
- Copper Thickness: 1oz on all layers
- Surface mount pads: 419
- Through holes: Quantity = 348, minimum size = 0.008 mil
- Soldermask: Green
- Legend: White on Top and Bottom layers
- Plating: Lead Free
- Finish: Best finish option for lead free
- Vendor Logo & date code: OK on back side
- Testing Needed: Yes
- Tolerances:

Plated-through holes under BGA chips +/- N/A  
All other plated-through holes +/- 0.003  
Metal to Metal +/- 0.003  
Legend to legend +/- no preference  
Soldermask to Metal +/- 0.003

### Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc

Layer  
Name

TOP METAL

TOP ASSEMBLY  
62mil Contour Route Cut

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"

MAXREFDES1523#	
Part Number:	
Rev 3	Maximum Integrated
Drill and Mechanical Layer	
JAN 17 2016 Units in mils	

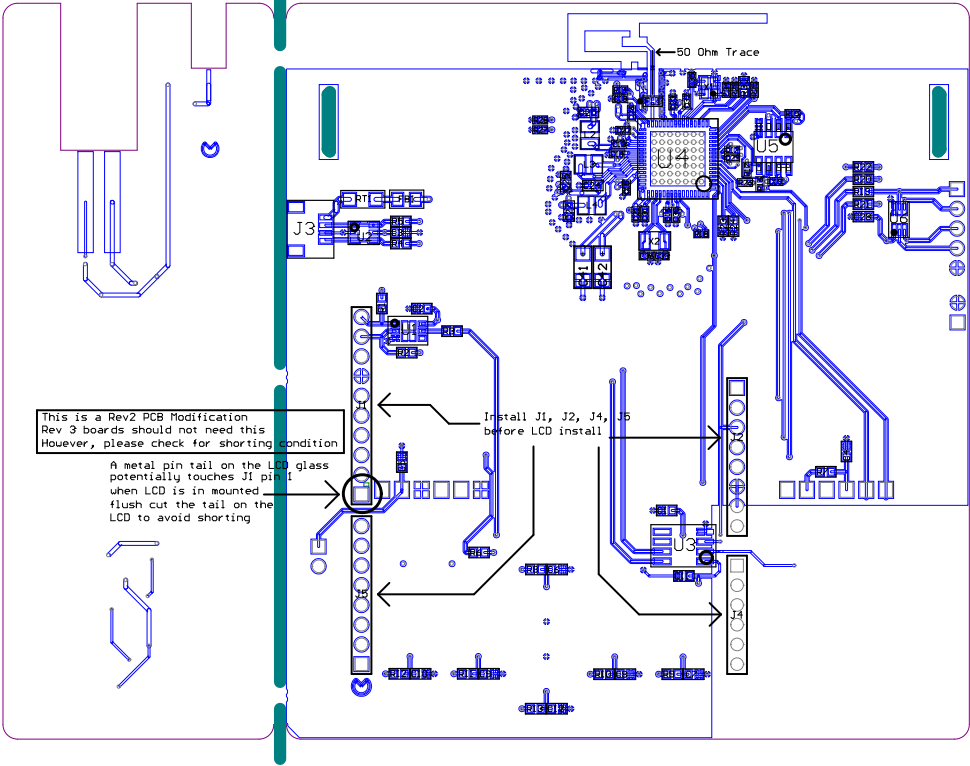
SHAPE	QTY	SIZE	SYM	PLATED TOLERANCE
ROUND	41	38	YES	+/- 0.003
ROUND	12	28	YES	+/- 0.003
ROUND	12	28	NO	+/- 0.003
ROUND	48	12	YES	+/- 0.003
ROUND	234	8	YES	+/- 0.003

- Notes:
1. Materials: RoHS Compliant FR-408 or similar laminate materials
  2. Board Dimensions: 4.889 x 3.730 mils
  3. Board Thickness: 0.062 mils +/- 20%
  4. Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
  5. Minimum Trace Width \ Trace Spacing: 10mil \ 6mil
  6. Copper Thickness: 1oz on all layers
  7. Surface mount pads: #18
  8. Through holes: Quantity = 348, minimum size = 0.000800 mil
  9. Soldermask: Green
  10. Legend: White on Top and Bottom layers
  11. Plating: Lead free
  12. Finish: Best finish option for lead free
  13. Vendor Logo & date code: OK on back side
  14. Testing Needed: Yes
  15. Tolerances:

Plated-through holes under BGA chips +/- 0.003  
 All other plated-through holes +/- 0.003  
 Metal to Metal +/- 0.003  
 Legend to Legend +/- no preference  
 Soldermask to Metal +/- 0.003

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.8 oz.Finished Copper
	Prep'd 0.010"
Layer 2 Power Plane	0.8 oz.Finished Copper
	Core 0.042"
Layer 3 Ground Plane	0.8 oz.Finished Copper
	Prep'd 0.010"
Layer 4 Bottom	1.0 oz.Finished Copper
	Prep'd 0.010"
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Weight	Copper	Single-bnd Controlled Impedance
Layer 1 TOP	0.8 oz	N/A	
Layer 2 Power Plane	0.8 oz	N/A	
Layer 3 Ground Plane	0.8 oz	N/A	
Layer 4 Bottom	1.0 oz	80 mil 0.018"	



Layer Stack Up Detail for: MAXREFDES1523Rev3.PcbDoc

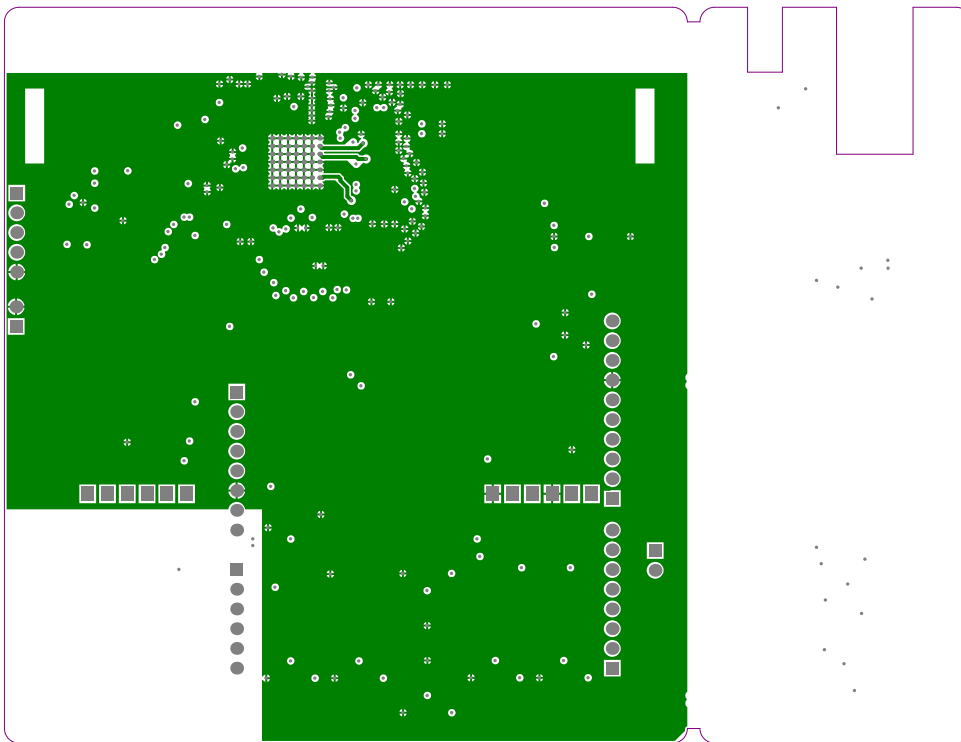
Layer Name


25mil Contour Route Cut

BOTTOM METAL

BOTTOM ASSEMBLY YJM322A MOTT08

BOTTOM METAL



MAXREFDES155#		
Part Number:		
	Property of maxim integrated	Rev 3
	Drill and Mechanical Layer	
JAN 17 2016	Units in mils	

SHAPE	QTY	SIZE	SYM	PLATED	TOLERANCE
ROUND	234	8		YES	+/- 0.003
ROUND	49	12		YES	+/- 0.003
ROUND	12	28		NO	+/- 0.003
ROUND	12	28		YES	+/- 0.003
ROUND	41	39		YES	+/- 0.003

#### Notes:

1. Material: RoHS Compliant FR-408 or similar laminate material
2. Board Dimensions: 4.889 x 3.730 mils
3. Board Thickness: 0.062 mils +/- 20%
4. Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
5. Minimum Trace Width / Trace Spacing: 10mil / 6mil
6. Copper Thickness: 1oz on all layers
7. Surface mount pads: 419
8. Through holes: Quantity = 348, minimum size = 0.008 mil
9. Soldermask: Green
10. Legend: White on Top and Bottom layers
11. Plating: Lead Free
12. Finish: Best finish option for lead free
13. Vendor Logo & date code: OK on back side
14. Testing Needed: Yes
15. Tolerances:
  - Plated-through holes under BGA chips +/- N/A
  - All other plated-through holes +/- 0.003
  - Metal to Metal +/- 0.003
  - Legend to legend +/- no preference
  - Soldermask to Metal +/- 0.003

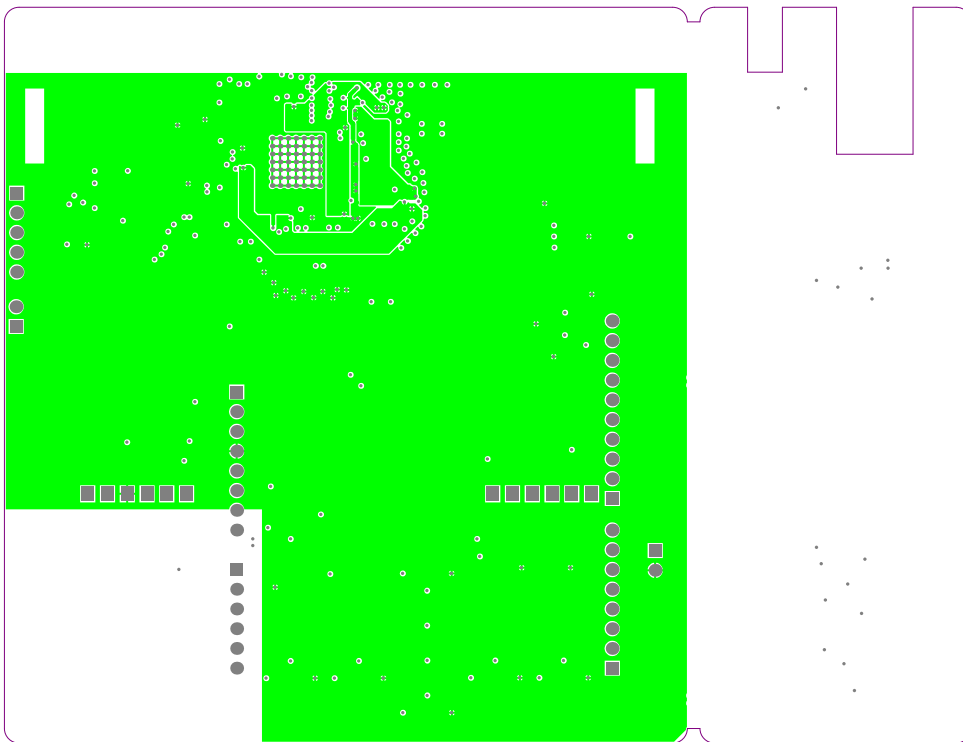



### Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc

Layer Name
GND PLANE

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"



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SHAPE	QTY	SIZE	SYM	PLATED	TOLERANCE
ROUND	234	8		YES	+/- 0.003
ROUND	49	12		YES	+/- 0.003
ROUND	12	28		NO	+/- 0.003
ROUND	12	28		YES	+/- 0.003
ROUND	41	39		YES	+/- 0.003

#### Notes:

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2. Board Dimensions: 4.889 x 3.730 mils
3. Board Thickness: 0.062 mils +/- 20%
4. Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
5. Minimum Trace Width / Trace Spacing: 10mil / 6mil
6. Copper Thickness: 1oz on all layers
7. Surface mount pads: 419
8. Through holes: Quantity = 348, minimum size = 0.008 mil
9. Soldermask: Green
10. Legend: White on Top and Bottom layers
11. Plating: Lead Free
12. Finish: Best finish option for lead free
13. Vendor Logo & date code: OK on back side
14. Testing Needed: Yes
15. Tolerances:

Plated-through holes under BGA chips +/- N/A  
All other plated-through holes +/- 0.003  
Metal to Metal +/- 0.003  
Legend to legend +/- no preference  
Soldermask to Metal +/- 0.003



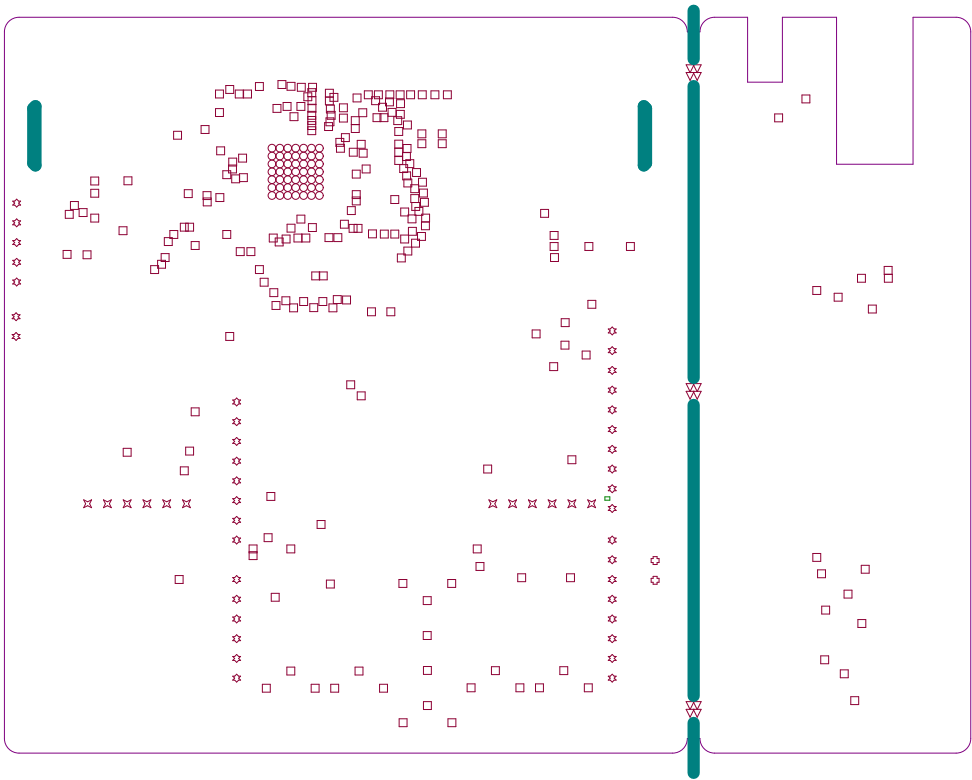
### Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc


Layer  
Name

SPLIT POWER PLANE

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"



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SHAPE	QTY	SIZE	SYM	PLATED	TOLERANCE
ROUND	234	8	□	YES	+/- 0.003
ROUND	49	12	○	YES	+/- 0.003
ROUND	12	28	▽	NO	+/- 0.003
ROUND	12	28	✕	YES	+/- 0.003
ROUND	41	39	✱	YES	+/- 0.003

#### Notes:

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2. Board Dimensions: 4.889 x 3.730 mils
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4. Layers: 4 (Top, Gnd Plane, Power Plane, Bottom)
5. Minimum Trace Width / Trace Spacing: 10mil / 6mil
6. Copper Thickness: 1oz on all layers
7. Surface mount pads: 419
8. Through holes: Quantity = 348, minimum size = 0.008 mil
9. Soldermask: Green
10. Legend: White on Top and Bottom layers
11. Plating: Lead Free
12. Finish: Best finish option for lead free
13. Vendor Logo & date code: OK on back side
14. Testing Needed: Yes
15. Tolerances:
  - Plated-through holes under BGA chips +/- N/A
  - All other plated-through holes +/- 0.003
  - Metal to Metal +/- 0.003
  - Legend to legend +/- no preference
  - Soldermask to Metal +/- 0.003



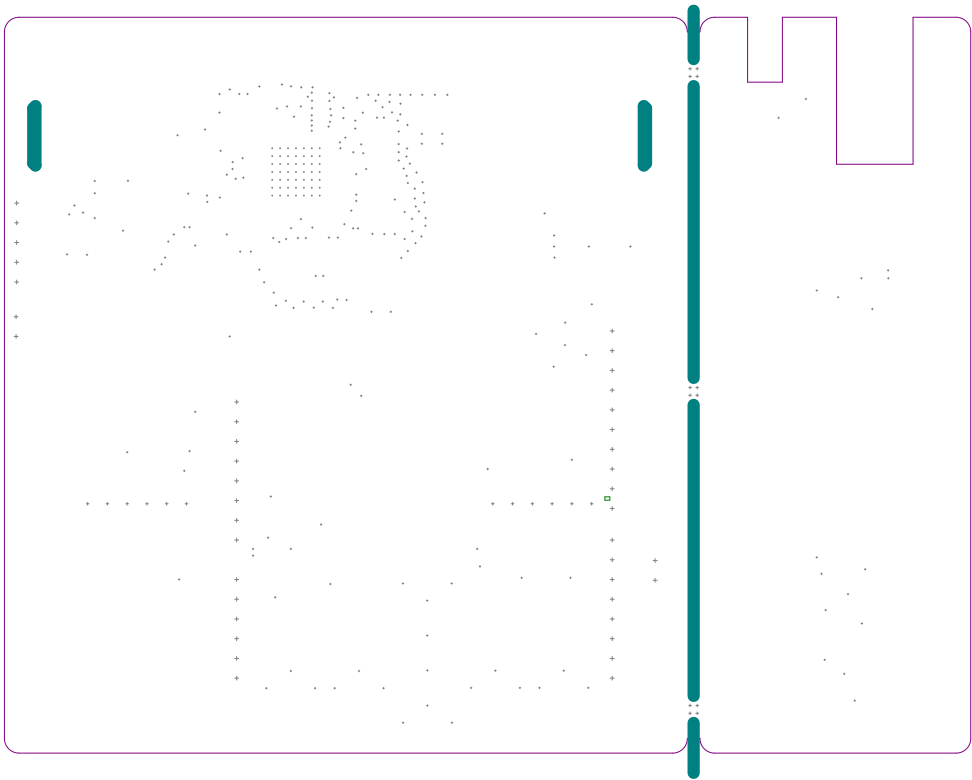
### Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc


Layer  
Name

62mil Contour Route Cut

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"



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SHAPE	QTY	SIZE	SYM	PLATED	TOLERANCE
ROUND	234	8	-	YES	+/- 0.003
ROUND	49	12	-	YES	+/- 0.003
ROUND	12	28	+	NO	+/- 0.003
ROUND	12	28	+	YES	+/- 0.003
ROUND	41	39	+	YES	+/- 0.003

Notes:

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2. Board Dimensions: 4.889 x 3.730 mils
3. Board Thickness: 0.062 mils +/- 20%
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5. Minimum Trace Width / Trace Spacing: 10mil / 6mil
6. Copper Thickness: 1oz on all layers
7. Surface mount pads: 419
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9. Soldermask: Green
10. Legend: White on Top and Bottom layers
11. Plating: Lead Free
12. Finish: Best finish option for lead free
13. Vendor Logo & date code: OK on back side
14. Testing Needed: Yes
15. Tolerances:
  - Plated-through holes under BGA chips +/- N/A
  - All other plated-through holes +/- 0.003
  - Metal to Metal +/- 0.003
  - Legend to legend +/- no preference
  - Soldermask to Metal +/- 0.003



Layer Stack Up Detail for: MAXREFDES155Rev3.PcbDoc

Layer  
Name

62mil Contour Route Cut

Silkscreen Top	
Soldermask Top	
Layer 1 TOP	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 2 Power Plane	0.5 oz.Finished Copper
Core 0.042"	
Layer 3 Ground Plane	0.5 oz.Finished Copper
Prepreg 0.010"	
Layer 4 Bottom	1.0 oz.Finished Copper
Soldermask Bottom	
Silkscreen Bottom	

Layer Name	Copper Weight	Single-End Controlled Impedance Ohm / Width
Layer 1 TOP	0.5 Oz	N/A
Layer 2 Power Plane	0.5 Oz	N/A
Layer 3 Ground Plane	0.5 Oz	N/A
Layer 4 Bottom	1.0 Oz	50 Ohm / 0.018"